ADLINK
Leading **EDGE COMPUTING**

Rugged & Ready

Aerospace and Defense Solutions

DiGiCOR

Even within the space of only a few hundred square meters, expect tomorrow's Internet of Battlefield Things (IoBT) to span an array of intelligent equipment, including long-range camera systems, environmental sensors, smart munitions, smart handheld weapons, wearable devices, body armor, robots, vehicles (both manned and autonomous), and more. There may be dozens of devices within each type, and each device may contain dozens of sensors, all relaying data into localized edge networks. These edge networks, in turn, may also be collecting data from drones, adjacent battle units, and a centralized operations center.

With potentially gigabytes rushing in per minute, that data deluge may prove paralyzing unless organizations have platforms and applications ready to convert it all into analyzed, actionable decisions. A complete strategy requires the ability to perform next-generation computing tasks today, with provisions for autonomy, size, weight, and power (SWaP) restrictions, mobility, and machine learning. With decades of experience in creating high-density, powerful, and scalable computing solutions for vertical markets – all based on commercial off-the-shelf (COTS) availability and best-in-class reliability – ADLINK now presents an end-to-end family of product groups for military and aerospace organizations.

ADLINK's ongoing commitment to industry groups, such as The Open Group FACE™ (Future Airborne Capability Environment), SOSA™ (Sensor Open Standards Architecture) Consortia, and the VITA Standards Organization (VSO), places us in a central position to ensure strict standards adherence while pushing innovation across the market.

The results of this involvement include close partnerships with key technology vendors. For example, ADLINK is a Premier member of the Intel® Internet of Things (IoT) Solutions Alliance, which provides ADLINK with a front row opportunity to obtain and integrate the most advantageous new CPU technologies for SWaP-sensitive IoT solutions. Similarly, as a rare member of multiple NVIDIA partnerships (including being an NVIDIA Quadro Embedded Partner, NVIDIA OEM Preferred Partner, and NVIDIA Jetson Preferred Partner), ADLINK stands positioned to embed the latest capabilities for massively parallelized workloads including radar, wide-area surveillance, and hyperspectral imaging.

Collectively, these partnerships contribute to ADLINK's industry-leading capabilities across the IoBT ecosystem, including coordinated, cross–platform solutions driven by Data Distribution Service (DDS) protocols. ADLINK excels at edge and artificial intelligence (AI) driven systems that comprise end-to-end, data-to-decision solutions for land, sea, and air deployments. From dense blade solutions for communications to tiny, GPU-accelerated servers for AI-enhanced analysis in the field, ADLINK delivers small form factor (SFF) products renowned for their efficiency, affordability, and ruggedness. When military and aerospace organizations need next-generation AIoT (AI-enhanced IoT) challenges solved, ADLINK has the answers.

The Situation in Five Points

1 As IoT pervades devices throughout field operations, the amount of incoming data will outstrip human ability to organize, examine, and analyze it all.

2 The analysis necessary to reach actionable outcomes from data must be assisted through automation, especially via machine learning and inference.

3 AI can increase the capability and value of most IoT implementations.

4 Military and aerospace applications benefit from AI enhancement, but this improvement must come with balancing maximum performance against SWaP limitations.

5 ADLINK specializes in crafting compact, high-performance, AI-ready computing platforms suited to the taxing demands of field deployment.

Blades & Platforms

For over 30 years, the computing industry has run along parallel paths, with one path catering to consumer needs, another to businesses, and a third targeting the specific requirements of embedded markets. Since embedded computing environments tend to place rigorous demands on systems, a host of system form factors, specifications, and priorities emerged to bring architectural consistency and COTS-friendly availability to solutions. The following examples showcase some of these form factors and how ADLINK has leveraged them, bridging legacy-minded compatibility with future-ready functionality.

CompactPCI

Defined by the PCI Industrial Computer Manufacturers Group (PICMG), the CompactPCI family of specifications encompasses 3U and 6U blade architectures, spanning everything from board dimensions to signaling and protocols. CompactPCI provides for designs featuring from two to 32 slots, and ongoing updates to the core specification enable higher-performance connectivity options, such as Serial RapidIO and PCI Express. Hot-swap support lets operators replace faulty blades without incurring system downtime, and lower power demands than conventional blade platforms, combined with extra ruggedness features, make CompactPCI a clear choice for military and aerospace implementers operating in less than ideal circumstances. For example, NASA selected CompactPCI as the foundation for the Mars Rover Curiosity's two primary computers, in part due to the specification's exceptional shock and vibration tolerances and its overall reliability. Similarly, the U.S. Army CAAS (Common Avionics Architecture System) adopted CompactPCI for its Chinook and Black Hawk helicopters' avionics systems, which must endure formidable and sustained rigors during missions.
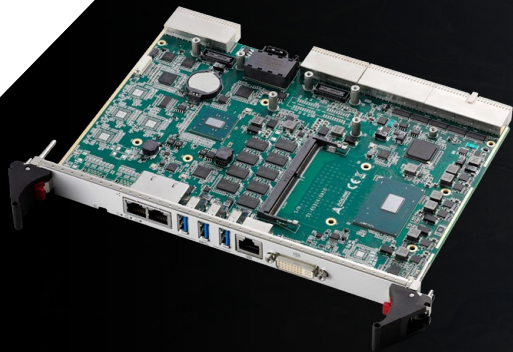
ADLINK 3U and 6U CompactPCI blades feature many of the latest Intel® Atom®, Intel® Core™, and Intel® Xeon® processors. For example, ADLINK's new cPCI-6636 processor blade features an Intel® Xeon® E31505M v5 processor (Intel® Core™ i7 and Core™ i3 options are also available), up to 32GB of DDR4-2133 memory, XMC support, and up to eight USB 3.0 and four Gigabit Ethernet ports. Alternatively, ADLINK's new cPCI-A3515 3U processor blade supports up to a quad-core Intel® Core™ i7-5700EQ processor, 16GB of DDR3L-1600 ECC memory, three independent display outputs, USB 2.0 and 3.0, and two Gigabit Ethernet ports. The cPCI-6636 emphasizes high integration and compute density while the cPCI-A3515, based on the CompactPCI Serial specification, adopts point-to-point serial connectivity to enable the higher I/O data rates expected for future applications. Both products highlight ADLINK's commitment to ruggedness, featuring optional support for extended operating temperatures from -40°C to +85°C (with Intel® cTDP), illustrating that CompactPCI remains impressively versatile for a host of tactical needs.

VPX

VPX is essentially a blade architecture reduced to 3U and 6U card-sized proportions, enabling multi-card enclosures roughly the size of a shoe box. This architecture can transplant demanding application workloads that until recently required much larger server systems into compact, SWaP-sensitive designs while still incorporating cutting-edge processors, such as Intel® Xeon® and NVIDIA Quadro. In form and function, VPX shares much in common with CompactPCI. However, traditional CompactPCI and CompactPCI Plus standards don't provide the sort of high-speed serial communications demanded by processor-intensive tasks, so VPX (based on the VITA 46 standard) rose in popularity owing to its support for high-speed serial fabrics. This is particularly true in military and aerospace markets. VPX can also accommodate components featuring low-power innovations and options, enabling ADLINK VPX systems to tackle the most modern, AI-centric applications with significantly lower power draw than legacy approaches.

The importing of advanced, server-class GPUs into such a diminutive form factor opens countless opportunities across massively accelerated general purpose GPU (GPGPU) computing. An image processing or radar analysis station that used to require a meter-thick stack of rackmount systems can now be carried in one arm. Moreover, a Quadro-enhanced GPGPU system will outperform an old, non-optimized solution while adhering to a host of industry specifications that ensure ruggedness, environmental tolerance, and interoperability with affordable COTS components.


For an example within ADLINK's VPX line, the 3U VPX3010 series packs formidable capability into a blade measuring only 100 x 160 mm (3.94 x 6.3 inches) while also meeting VITA specifications for ruggedized implementation and the VITA 65 OpenVPX framework. VPX3010 models feature the Intel® Xeon® processor D-1500 SoC (formerly "Broadwell-DE"), with up to 12 cores able to run within a 45W power envelope. ADLINK adds up to 32GB of surface-mounted DDR4-2133 dual-channel ECC memory and an onboard SLC SATA SSD of up to 64GB. Despite its small SoC form factor, the VPX3010 is expandable via one PCI Express x8 Gen3 XMC expansion slot, two 6 Gb/s SATA ports, a range of USB, serial, GPIO, and VGA ports, and rear I/O networking (two 10GBASE-KX4 and either two 1000BASE-T or one 1000BASE-T and two 1000BASE-BX by BOM option). The cards also support PCIe x16 Gen3 through a non-transparent bridge for peer-to-peer communication, depending on BOM options.

With this amount of small form factor flexibility, VPX finds its way into solutions from in-flight analysis of many unmanned aircraft system (UAS) input streams to advanced radar signal processing in air-defense and guided missile systems.

PC/104

In 1992, twelve of the computing industry's top systems companies formed the PC/104 Consortium to help adapt proven desktop technologies into embedded applications. One of these founders, Ampro, brought 16 years of PC/104 leadership and innovation when ADLINK Technology acquired it in 2008. As a compelling alternative to the blade and card model, PC/104 and its many evolved variant standards present a 90 x 96 mm system-on-board platform that allows integrators to stack cards like building blocks, one connected to the next, and combine their functionality across shared interconnects. The stacking nature of PC/104 enables exceptional stability and reliability within high-vibration environments, and ADLINK offers "Extreme Rugged" models with temperature tolerances from -40°C to +85°C.
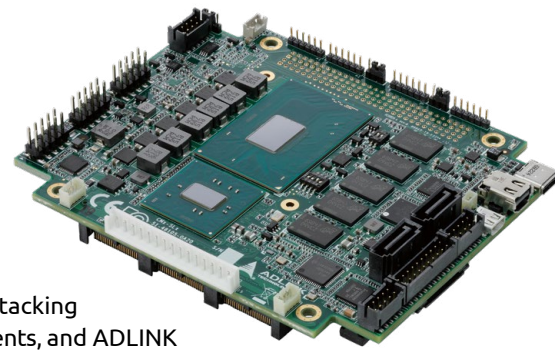
For modern, low-power applications, ADLINK's CMx-SLx motherboard offers the 6th Generation Intel® Core™ processor i3-6102E (2 cores, 1.9 GHz, 25W TDP), although variant models feature the Intel® Core™ i3-6100E (2 cores, 2.7 GHz, 35W) and the Intel® Xeon® E3-1505L v5 (4 cores, 2.0/2.8 GHz, 25W). Graphics are provided by Intel's ninth-generation integrated graphics core, which features ample video decode acceleration and simultaneous triple-display output across HDMI, DisplayPort, and LVDS. ADLINK supplies 8GB or 16GB of surface-mounted DDR4-ECC RAM and a range of onboard SLC- or MLC-based SSD storage from 8GB to 64GB. Gigabit Ethernet, two 6 Gb/s SATA ports, one USB 3.1 port, six USB 2.0 ports, and a Trusted Platform Module (TPM) round out the CMx-SLx's high-performance, security-minded capabilities.

For more forward-looking applications that can benefit from GPGPU acceleration, consider ADLINK's PCIe/104-based CM5-P1000. The board features an NVIDIA Quadro P1000 GPU, equipped with 640 CUDA cores and backed by 4GB of GDDR5 memory. This provides for 1.8 TFLOPS performance with output across four HDMI connections.

COM Express

In consumer systems, it's not unusual to upgrade motherboards every two to three years as processors and other technologies advance, offering more speed and features. However, in embedded markets such as military and aerospace, a motherboard replacement presents greater challenges. Longer system viability times mean that replacing a motherboard may entail replacing several add-in cards and possibly even the case, meaning less convenience, longer servicing time, and higher expense. The COM Express form factor arose to minimize such issues. By placing core processing components on a small card that fits onto a larger carrier board containing most I/O features, COM Express makes swapping out cards and upgrading key processing performance quick and simple.
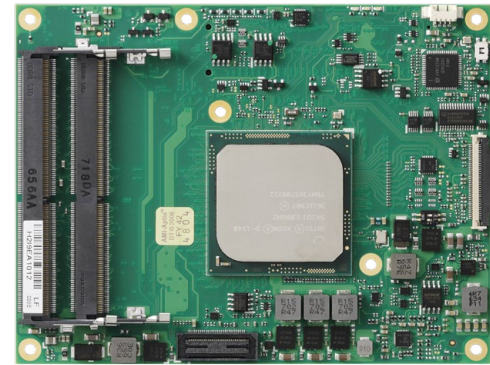
ADLINK's Express-BD7 adheres to the recent COM Express Type 7 specification intended for data center, server, and high-bandwidth video applications. The module supports conventional and low-power 16-core Intel® Xeon® D processor series , a maximum of 32GB of DDR4 memory, and two 10GbE LAN connections. Additionally, the module provides for USB 3.0, SATA 6Gb/s, Intel® TXT and TPM security, and PCI Express expansion. Since graphics typically aren't needed in the server apps addressed by the Type 7 specification, all graphics interfaces have been removed to further lower power needs and free up pins for additional networking. The Express-BD7 excels in environments from embedded systems in the rugged tundra to hot aisles in the densest data centers. Not least of all, ADLINK integrates Smart Embedded Management Agent (SEMA) middleware on its Type 7 carrier board management controller, which in turn enables ADLINK's SEMA Cloud for remote and predictive maintenance.

| Embedded MXM Graphics Modules |
| --- |
| EGX-MXM-P1000 |
| EGX-MXM-P3000 |
| EGX-MXM-P3000 |
| EGX-MXM-P5000 |

MXM-Based Board/Platforms
PCIE-GIENVQ
VPX3-P5000
cPCI-R6500D
HPERC VITA-75
AVA-5500
ADi-SC1X
DLAP-3000-CFL
MVP-5100-MXM
MVP-6100-MXM

MXM

Because mobile and small form factor systems need the same modular graphics abilities as full-size solutions but obviously lack the space for conventional add-on cards, NVIDIA led the development of the Mobile PCI Express Module (MXM) specification. MXM allows integrators to select from a wide range of mobile-optimized GPUs, which increases solution flexibility and reduces qualification times while keeping SKU counts low.

MXM-based GPUs can be used across a broad range of solutions, including PCI Express modules, server blades, and rugged HPERC systems. Artificial intelligence systems and IoBT applications in particular often excel with GPU assistance. In fact, any application that needs GPU-based acceleration and/or visualization, from ground-based signal analysis to in-air drone autonomy, can benefit from a range of ADLINK MXM product options.
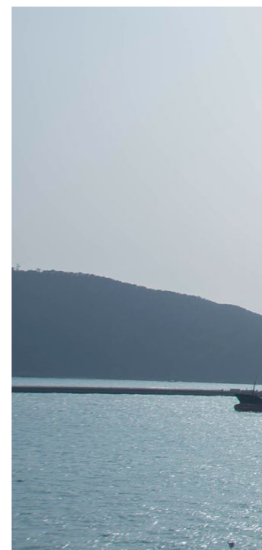
ATCA

The Advanced Telecommunications Computing Architecture (AdvancedTCA, or ATCA) emerged from the PICMG as a set of specifications governing carrier-grade communications equipment. More recently, ATCA has migrated into the military and aerospace sectors on the strengths of its ruggedized physical characteristics, high processing density, and high-bandwidth communication fabrics. For example, ATCA blades feature metal panels designed to inhibit RF interference and minimize fire risk. Blade spacing typically accommodates 14 boards in a 19-inch, 12U or 13U enclosure. Solution fabrics can include up to 100G Ethernet, Fibre Channel, PCI Express, InfiniBand, and Serial RapidIO.

ADLINK manufacturers a full line of ATCA solutions spanning processor blades, switch blades, Rear Transition Modules (RTM), and complete ATCA platforms. These platforms can address a wide range of military and aerospace communication needs, including mobile data offloading for areas with constrained or security-restricted mobile data access.

CSA

Cyber security appliances (CSAs) round out ADLINK's line of communication server solutions. Whereas ATCA products focus on compute density via blade architecture, CSA solutions focus on network density. Working within the framework of a dual-processor server in a 2U rackmount form factor, ADLINK created its own series of Network Interface Module (NIM) offerings. NIMs containing from one to four ports slot into any of the appliance's four or eight (depending on the model) front-facing NIM bays, allowing for extreme flexibility in configuration and scaling as more/faster ports become needed. Available bandwidths and interface types span from 1 to 100 Gigabit Ethernet across copper, SFP, SFP+, QF+, and QSFP28 connections.

Beyond the NIM architecture, ADLINK's CSA solutions offer a formidable selection of component options. Buyers of the CSA-7210, for example, can select from a range of Intel® Xeon® Silver and Gold processors, with up to 18 cores per CPU. Sixteen DDR4 slots enable up to 512GB of total system memory, and three 3.5" SATA bays plus one hot-swappable 3.5" SATA bay provide potentially tens of terabytes of RAID-protected storage. Options include 100 Gb/s Intel QuickAssist Technology, a TPM for higher platform security, and a 128 x 32, button-equipped graphic display for easier maintenance.

The application range for CSA systems is remarkably broad. In one major Asia-Pacific metropolis, AppEx Networks selected a fleet of 4U ADLINK CSA-7400 systems as the backbone for its software-defined wide area network (SD-WAN) solutions and services. An SD-WAN can connect LANs, data centers, cloud services, and Internet applications on a regional or global scale. The abstraction of network functions from their underlying hardware resources allows admins to improve link reliability and performance across the WAN; construct virtualized, dedicated, high-bandwidth links for specific projects or purposes; achieve five-nines availability; perform dynamic, automated load balancing; and execute operations such as firewalling or deep packet inspection (DPI) as services free from dedicated appliances. CSA-7400 systems provide the hardware foundation for all of this. Features include up to 800G of front panel I/O divisible across up to 72 interfaces, redundant power supplies, real-time out-of-band monitoring and management, and high-density processing from up to four compute nodes stocked with dual Intel® Xeon® E5-2600 v3/v4 processors or Intel® Xeon® Scalable processors.

SFF Tactical EDGE Server Group

With many years of experience in manufacturing computing solutions for the toughest military environments, ADLINK formed its Small Form Factor Tactical Edge Server (SFF-TES) solution group to better optimize products for one of the most in-demand and mission-critical computing needs: small systems that can handle both the data loads and physical pounding common in edge and fog deployments. SFF-TES solutions focus on balancing SWaP constraints against high compute performance and scalability. Some of our current and coming flagships include:

HPERC

ADLINK's HPERC line exemplifies how the company's integrated research, design, and manufacturing capabilities can yield exceptionally versatile solutions for military and aerospace needs. The HPERC line features remarkably compact systems that emphasize high performance, convection cooling, ruggedness, adherence to a range of military standards, and versatile scalability. HPERC systems can endure prolonged exposure in extreme, turbulent environments and a reliable, high-bandwidth backbone for edge networks.

Consider ADLINK's HPERC-KBL. Like all HPERC solutions, this HPERC system features VITA 75-standard mounting, silent passive cooling, and measurements of only 223.7 x 177.8 x 68.7 mm (8.8 x 7.0 x 2.7 inches). Despite its diminutive size, the HPERC-KBL features a quad-core Intel® Xeon® processor combined with 16GB of ECC DDR4 memory. This ample processing capability can be further enhanced with optional MXM graphics for GPGPU-accelerated applications. Removable SATA and SD storage provide data collection capability, while four Gigabit Ethernet ports, six USB ports, and MIL-DTL-38999 connectors offer all the network and device connectivity required in demanding edge settings.

ADLINK HPERC solutions enable advanced applications in the toughest environments, such as when one defense system provider integrated an HPERC system into its medium-altitude reconnaissance surveillance system, a military plane designed to perform a range of airborne intelligence gathering for informing field personnel actions. The craft employs a formidable range of sensors, including thermal imaging, up to four HD video cameras, and multiple radio frequencies. Feeds from all these sensors flow into the high performance, rugged HPERC system. This makes the mission-critical computing system fast enough to handle image and signal processing across all input streams in real-time and beam them to waiting teams for immediate action.

SETO

Some applications require server-class processing and reliability but with even more attention to environmental endurance. ADLINK's SETO-1000 kicks off a new product line for ADLINK that focuses on IP65 protection against dust and water intrusion while housing up to two CPUs in a thin, all-aluminum chassis cooled entirely by conduction. SETO is built for outdoor ruggedness, operating in temperatures from -40°C to 55°C and with ambient operational vibration of 5Hz ≤ f ≤ 9Hz (up to 3.5mm displacement) and 9Hz ≤ f ≤ 150 Hz @ 1g (EN61131-2).

In a system only 44 mm thick, the SETO-1000 features up to two 10-core Intel® Xeon® E5-2400 series processors. Accompanied by six DDR3 slots (up to 48GB per CPU) and a board-mounted SATA drive of up to 256GB, the SETO-1000 also features considerable expansion capability. The system integrates two Gigabit and two 10G Ethernet ports, two hot-swappable SATA bays, and a DisplayPort that converts to USB and serial ports via breakout cable. Existing SETO-1000 deployments include tower-mounted field base communications processing, outfitting an armored vehicle with enhanced reconnaissance and communication capabilities (including satellite and 4G/LTE/5G connections), and both radar image processing and multi-channel communications within the high vibration and shock environment of an Airborne Early Warning & Control (AEW&C) aircraft.

AVA-5500

AI continues to drive the next wave of applications able to transform productivity and safety. By pairing the performance of an Intel® Core™ i7 processor with the task-specific parallel processing of an NVIDIA Quadro GPU, ADLINK has crafted a deceptively small yet specifically powerful platform for harnessing deep learning to analyze visual data. The compact AVA-5500 is specifically designed for reliable, 24x7 operation in rugged environments. Features such as wide-range DC input, passive chassis cooling, four locking DisplayPort outputs, and eight M12-type Gigabit Ethernet ports (four of which support PoE) ensure that the AVA-5500 can handle critical applications without the random failures that can plague less rigorously optimized designs.

As an example of the AVA-5500's strengths, ADLINK helped a leading railway integrator deploy the system on a special rail inspection train to process captured images in real-time. The images ran through an AI application that could determine if wayside equipment would fail when train speeds reached 120 km/h. If so, maintenance crews were immediately notified. Related AI-driven visual applications for the AVA-5500 include spotting suspicious behaviors within a crowd and performing post-event analysis. In another application, the AVA-5500 was deployed by a major airport operator at the heart of its enhanced video surveillance system (EVS). Leveraging the AVA-5500's rugged, fanless design and AI-enabled video analytics capabilities, the EVS system provides real-time intuitive monitoring of the airport, and automatic detection of foreign objects on the runways and taxiways, enhanced by improved visibility during night and adverse weather, remarkably increasing airport safety, security and operational efficiency.

SFF Tactical Edge Server Nano and Xavier

ADLINK understands that small-scale computing can yield massive results in key applications, and AI will drive in many such applications across military and aerospace in the coming years. Palm-sized, self-organizing drone swarms and autonomous, landmine-scanning robots are just two examples. While many of the above products are small enough to tuck under one arm, applications will demand ever-smaller solutions. This is why ADLINK is now productizing NVIDIA's Nano and Xavier platforms as part of its SFF Tactical Edge Server program.

Nano and Xavier fall under NVIDIA's Jetson line of Maxwell architecture system-on-module embedded computing boards, which target deep learning applications that require low power envelopes. The Jetson Nano measures only 70 x 45 mm and is powered by a quad-core ARM Cortex-A57 MPCore processor, 4GB of LPDDR4 memory, a 16GB eMMC SSD, Gigabit Ethernet, and a range of modern I/O and display options. With 128 CUDA cores in play, Nano can perform an array of parallel processing for graphical analysis and deep learning tasks.

For an example of one way ADLINK is now adapting Nano, look to the ADLINK M100-Nano-AINVR. Measuring 210 x 170 x 55 mm, the M100-Nano-AINVR comes equipped with eight PoE-enabled Gigabit Ethernet ports and a tray-mounted 2.5" SATA drive bay, making this a highly optimized solution for multi-stream IP camera input and AI-powered network video recorder (NVR). This solution can be a perfect part of deploying camera vision at the network edge for faster time-to-decision.

NVIDIA's 105 x 105 mm Jetson AGX Xavier module elevates Jetson to a higher level. Based on the Tegra Xavier processor (featuring eight Carmel cores and 512 CUDA cores), 16GB of RAM, and 32GB of eMMC integrated storage, Jetson AGX Xavier includes a breakout board offering ports from USB-C 3.1 to MIPI CSI-2 (for cameras) to Gigabit Ethernet. Also included are a PCIe x16 Gen4 slot as well as an M.2 x1 slot, which can easily enable functions such as mobile wireless data connectivity.

NVIDIA has taken great care to optimize Xavier for vision acceleration and machine inference, and ADLINK is now capitalizing on this with designs such as its M300-Xavier-ROS2. This heterogeneous computing system is rich in I/O ports and expansion options, including HDMI output, twin Gigabit Ethernet ports, and MIPI CSI. The M300-Xavier-ROS2 works with many Linux distributions and arrives ready for field deployment in AI inference and/or training roles.

Expect to see more Jetson-based, VITA 75-compliant solutions from ADLINK soon for a broad spectrum of military and aerospace needs.

Why ADLINK?

ADLINK provides defense and aerospace system integrators with extensive, highly cost-effective, military standards-compliant COTS/MOTS products. Built with uncompromised integrity and security, ADLINK designs and manufacturers its solutions in-house. Our vertically integrated production infrastructure provides customers with fast development and deployment of reliable, long-lifecycle products that enable rapid data-to-decision and end-to-end solutions for mission-critical applications. ADLINK's approach also facilitates system upgrades and technology insertions through unmatched customer proximity, best-in-class ODM capabilities, and industry-appropriate supply longevity.

Technology Leadership
As a long-standing pioneer in embedded technologies, ADLINK demonstrates strong thought leadership in leading industry consortia such as PICMG, PC/104, and VITA. The company also drives standards establishment and technology advancements to enable state-of- the-art SFF solutions for increasing mobility and SWaP challenges in the defense industry.

Extensive Portfolio
ADLINK is dedicated to continued development of its extensive, highly cost-effective, military standards-compliant COTS/MOTS product lines and leveraging edge computing, IoT, AI, and machine learning technologies to enable a wide range of data-to-decision, end-to-end, mission-critical solutions that address increasingly challenging and complex military deployments.

Strategic Partnership
As a Premier member of the Intel® Internet of Things Solutions Alliance, and NVIDIA Quadro Embedded Partner, OEM Preferred Partner and Jetson Elite Partner, ADLINK leverages unrivalled access to advanced processing technologies, driving innovative, open standards-based heterogeneous computing solutions for next-generation applications.
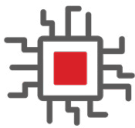
Quality and Integrity
With world-class in-house manufacturing facilities, established quality management systems, and supply chain management (ISO-9000, TL9000 certified, ITAR registered), ADLINK ensures uncompromised military-grade quality, and equally importantly, fully controls product integrity and security, and is thus immune to any outside tampering.

Supply Longevity
ADLINK ensures best practices in product obsolescence and lifecycle management. We leverage strategic partnerships with key component and software vendors, delivering supply longevity to support traditionally long lifecycle defense programs.

Business Flexibility
As an ODM powerhouse with a flexible and agile organization, ADLINK can effectively and efficiently address rebranding, customization, and joint development smoothly and promptly. ADLINK makes ease of doing business one of our top priorities and is focused on helping customers speed time-to-market for long-term mutual success.

Global Support
As a global enterprise with a strategic footprint in design, manufacturing, and service worldwide, ADLINK leverages customer proximity to effectively deliver products to regional market specifications and requirements. This high-touch business model, which hinges on local technical and business services, is key to most defense programs.

intel IoT Solutions Alliance Premier

NVIDIA PREFERRED PARTNER

NVIDIA QUADRO CERTIFIED · EMBEDDED

SOSA™ Sensor Open Systems Architecture

FACE™ Future Airborne Capability Environment

VITA Open Standards, Open Markets

VPX™

PICMG®

COM Express

CompactPCI®

PC/104 Embedded PC Modules

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